| | | | |
|---|---|---|---|
| Isolation Voltage | $V_{iso}$ | 3750 " | Vrms |
| Operating Temperature | $T_{opr}$ | -55~+110 | |
| Storage Temperature | $T_{stg}$ | -55~+125 | |
| Soldering Temperature | $T_{sol}$ | 260 | |

NOTE1:100 s pulse, 100Hz frequency
NOTE2:AC for 1minute, R.H.=40~60%

## ELECTRICAL CHARACTERISTICS (Temperature=25°C)

| Parameter | | Symbol | Condition | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|---|
| Input | Forward Voltage | $V_F$ | $I_F$=10mA | - | - | 1.4 | V |
| | Reverse Current | $I_R$ | $V_R$=6V | - | - | 1 | A |
| | Terminal Capacitance | $C_t$ | V=0, f=1kHz | - | 10 | - | pF |
| Output | Collector-Emitter dark current | $I_{CEO}$ | $V_{CE}$=10V, $I_F$=0 | - | - | 100 | nA |
| | Collector-Emitter breakdown voltage | $BV_{CEO}$ | $I_C$=0.1mA $I_F$=0 | 40 | - | - | V |
| | Emitter-Collector breakdown voltage | $BV_{ECO}$ | $I_E$=0.1mA $I_F$=0 | 6 | - | - | V |
| Transfer Characteristics | Current transfer ratio | CTR ' | $I_F$=1mA $V_{CE}$=2V | 600 | - | 7500 | % |
| | Collector-Emitter Saturation Voltage | $V_{CE(sat)}$ | $I_F$=20mA $I_C$= 5mA | - | 0.8 | 1 | V |
| | Isolation resistance | $R_{IO}$ | DC500V 40~60%R.H. | $10^{12}$ | $10^{14}$ | - | |
| | Floating Capacitance | $C_{IO}$ | V=0, f=1MHz | - | 0.4 | 1 | pF |
| | Cut-off Frequency | $f_c$ | $V_{CE}$=5V, $I_C$=10mA $R_L$ -3dB | - | 1 | - | kHz |
| | Rise Time | $t_r$ | $V_{CE}$=2V, $I_C$=10mA $R_L$ | - | 95 | 300 | s |
| | Fall Time | $t_f$ | | - | 84 | 250 | s |

## Characteristics Curves

**FIG.1:** Forward Current vs. Ambient Temperature

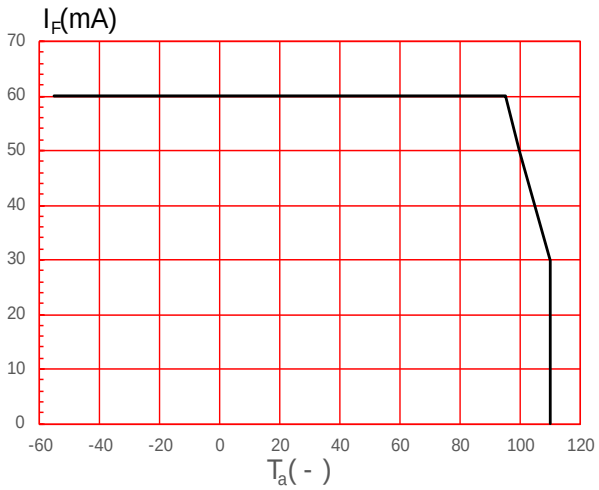



**FIG.2:** Collector Power Dissiption vs. Ambient Temperature



**FIG.7:** Normalized Current Transfer Ratio vs.

## Test Circuits

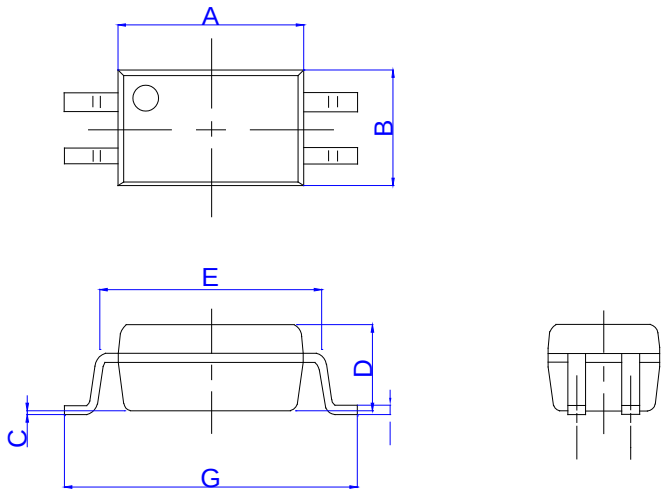
**FIG.12:** Test Circuits of Response Time

**FIG.13:** Curves of Response Time

**FIG.14:** Test Circuits of Frequency Response

Package Dimension (Unit: mm)

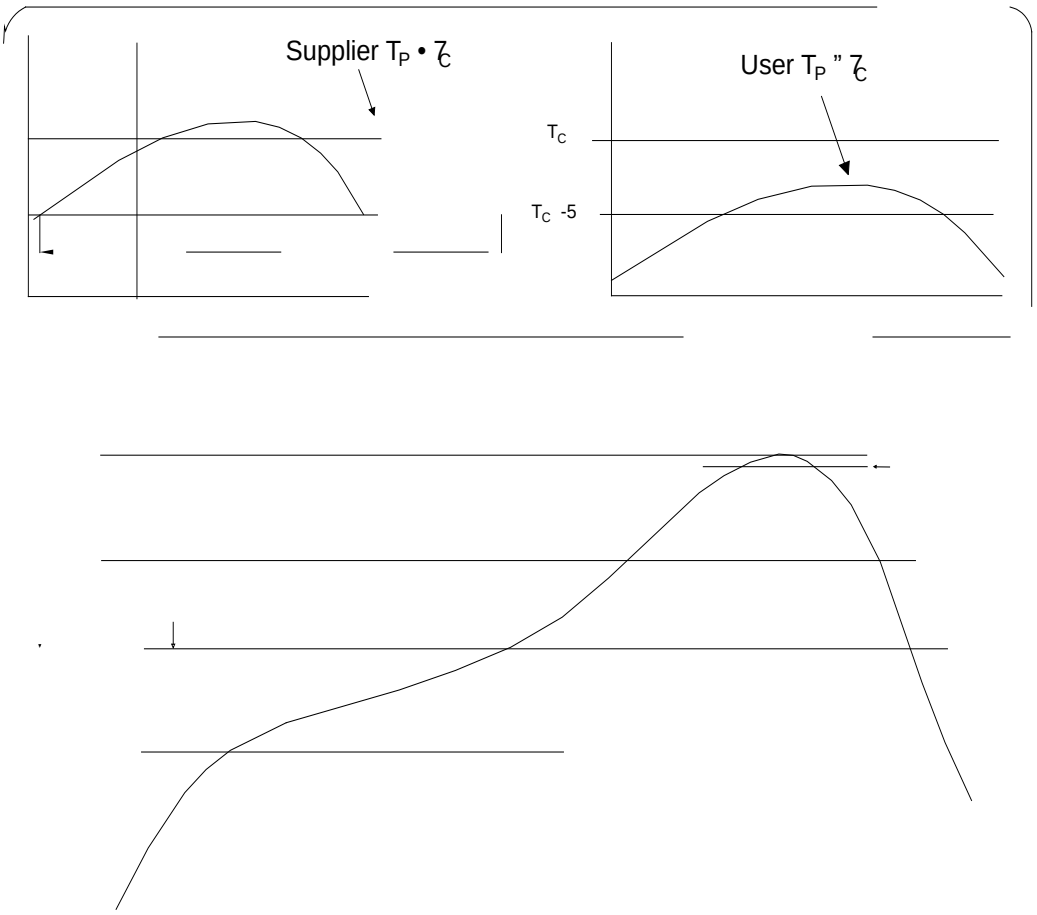
**Standard SSOP4 Type:**



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1

REFLOW INFORMATION (Pb-free)



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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